

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Hyung-suk CHOI</td> <td>04/18/2012</td> </tr> <tr> <td>Hyun-tae JUNG</td> <td>04/18/2012</td> </tr> <tr> <td>Eung-ryul PARK</td> <td>04/18/2012</td> </tr> <tr> <td>Da-soon LEE</td> <td>04/18/2012</td> </tr> </tbody> </table>		Name	Execution Date	Hyung-suk CHOI	04/18/2012	Hyun-tae JUNG	04/18/2012	Eung-ryul PARK	04/18/2012	Da-soon LEE	04/18/2012
Name	Execution Date										
Hyung-suk CHOI	04/18/2012										
Hyun-tae JUNG	04/18/2012										
Eung-ryul PARK	04/18/2012										
Da-soon LEE	04/18/2012										
RECEIVING PARTY DATA											
Name:	MAGNACHIP SEMICONDUCTOR, LTD.										
Street Address:	1, Hyangjeong-dong, Hungduk-gu, Chungbuk										
City:	Cheongju-si										
State/Country:	KOREA, REPUBLIC OF										
PROPERTY NUMBERS Total: 1											
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13465593</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13465593						
Property Type	Number										
Application Number:	13465593										
CORRESPONDENCE DATA											
Fax Number:											
Phone:	202-429-0020										
Email:	info@nsiplaw.com										
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>											
Correspondent Name:	NSIP LAW										
Address Line 1:	1156 15th St, NW Ste 603										
Address Line 4:	Washington, DISTRICT OF COLUMBIA 20005										
ATTORNEY DOCKET NUMBER:	5001.0059										
NAME OF SUBMITTER:	S Laura Chung										
Total Attachments: 2 source=NewApp_50010059_20120507LFC_AssingmentExecuted#page1.tif source=NewApp_50010059_20120507LFC_AssingmentExecuted#page2.tif											

OP \$40.00 13465593

ASSIGNMENT

For valuable consideration, we,

Hyung-suk CHOI	214-1106, Hyundai 2-cha, Bokdae-dong, Heungdeok-gu, Cheongju-si, Chungcheongbuk-do, Republic of Korea
Hyun-tae JUNG	304, Goldengrivil, 2548-1, Bongmyeong-dong, Heungdeok-gu, Cheongju-si, Chungcheongbuk-do, Republic of Korea
Eung-ryul PARK	202-303, Kumho Eoullim Apt., Bokdae-dong, Heungdeok-gu, Cheongju-si, Chungcheongbuk-do, Republic of Korea
Da-soon LEE	112-1402, Kumho Eoullim Apt., Bokdae-dong, Heungdeok-gu, Cheongju-si, Chungcheongbuk-do, Republic of Korea

hereby assign to:

MAGNACHIP SEMICONDUCTOR, LTD., a Republic of Korea

corporation/institution/foundation/institute having principal executive office(s) or place of business at: 1, Hyangjeong-dong, Hungduk-gu, Cheongju-si, Chungbuk, Republic of Korea; and

its successors and assigns (collectively hereinafter called "the Assignee"), the entire right, title and interest throughout the world in the inventions and improvements which are subject of U.S. Patent Application Number 13/465593 filed May 7, 2012 at the U.S. Patent & Trademark Office signed by us, with title ISOLATION STRUCTURE, SEMICONDUCTOR DEVICE HAVING THE SAME, AND METHOD FOR FABRICATING THE ISOLATION STRUCTURE, and we authorize and request the attorneys appointed in said application to hereafter complete this assignment by inserting above the filing date and application serial number of said application when known; this Assignment including said application, any and all United States and foreign patents, utility models, and design registrations granted for any of said inventions or improvements, and the right to claim priority based on the filing date of said application under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes; and we authorize the Assignee to apply in all countries in our name or in its own name for patents, utility models, design registrations and like rights of exclusion and for inventors' certificates for said inventions and improvements; and we agree for ourselves and our respective heirs, legal representatives and assigns, without further compensation to perform such lawful acts and to sign such further applications, assignments, preliminary statements and other lawful documents as the Assignee may reasonably request to effectuate fully this Assignment.

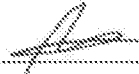
IN TESTIMONY/WITNESS WHEREOF, we, undersigned inventors (Assignors) intending to be legally bound, have hereto affixed our signatures.

This 10 day of April, 2012



Signature: Hyung-suk CHOI

This 16 day of April, 2012



Signature: Hyun-tae JUNG

This 18 day of April, 2012



Signature: Eung-ryul PARK

This 18 day of April, 2012



Signature: Da-soon LEE